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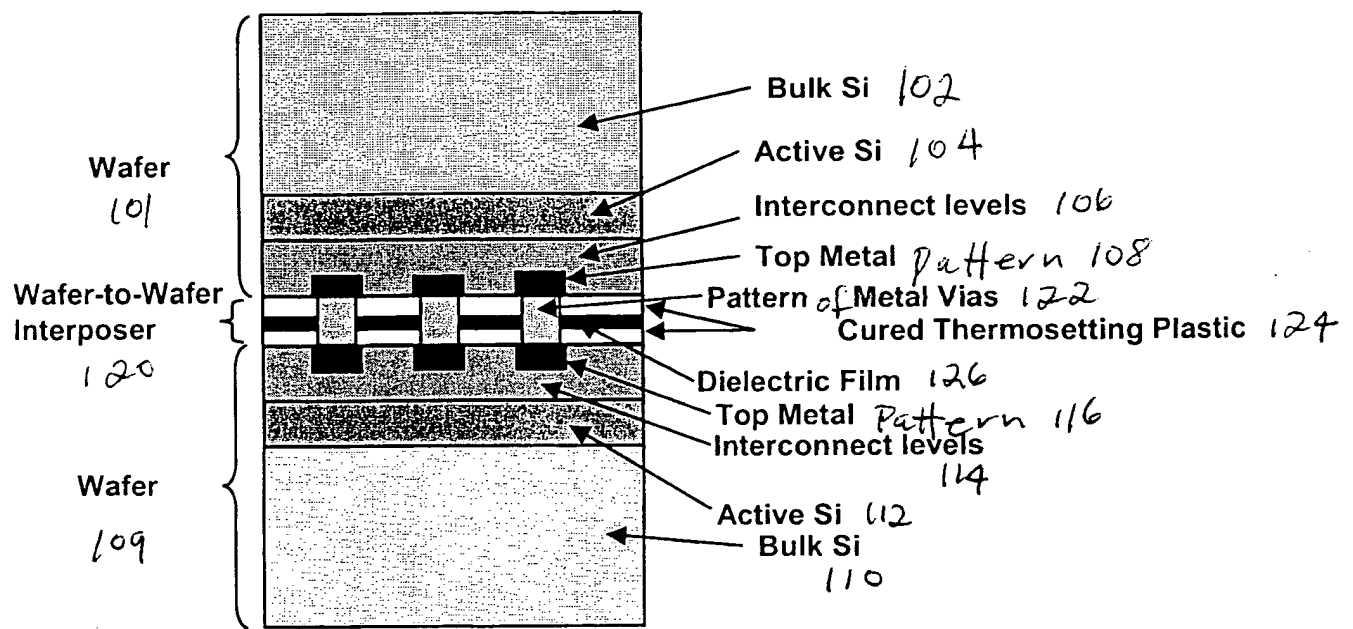
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200

Figure 2

Remove bottom release layer from pre-assembly interposer 300

~ 202

Align the pattern of metal vias 122 with the metal pattern 116 on the wafer 109

~ 204

Laminate pre-assembly interposer 400 to the wafer 109

~ 206

Remove top release layer from the pre-assembly interposer 400

~ 208

Align metal pattern 108 with the pattern of metal vias 122

~ 210

Cure uncured thermosetting plastic film 306 bond wafer 101 with the wafer 109; electrically couple the metal pattern 108 to the metal pattern 116

~ 212

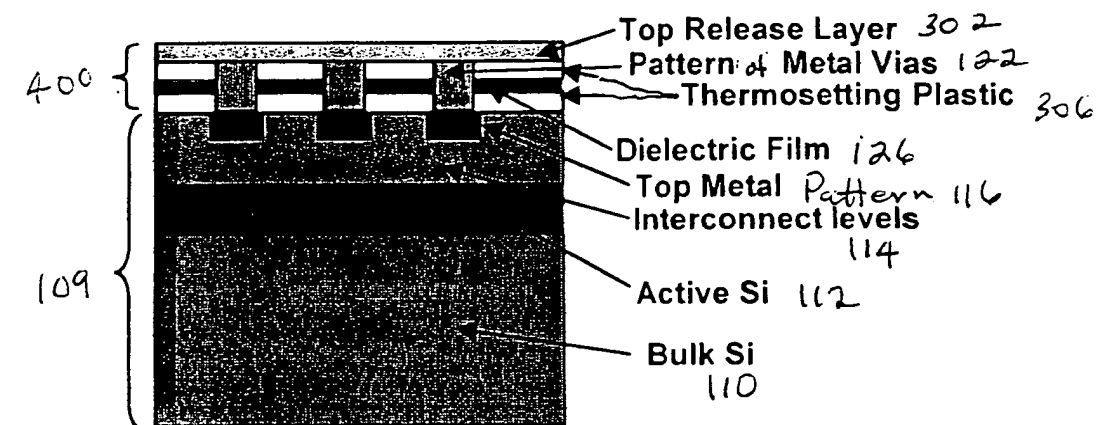
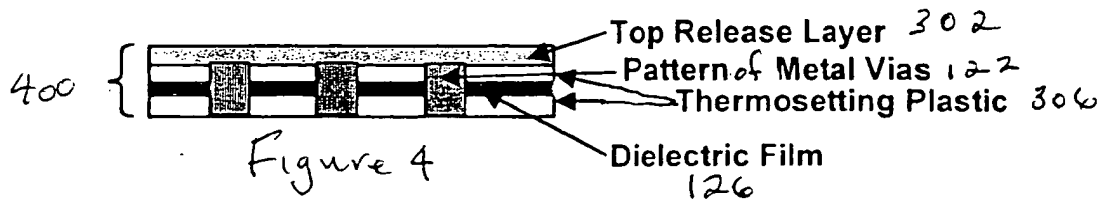
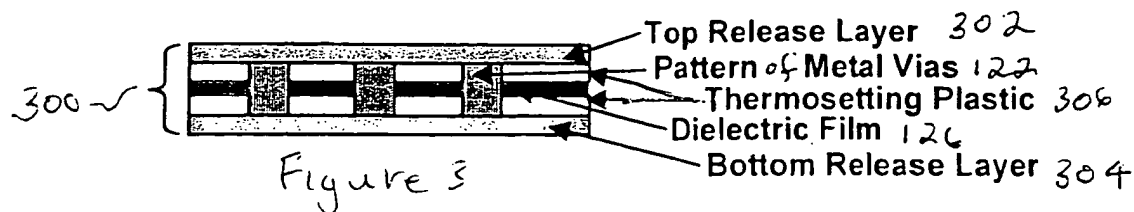


Figure 5

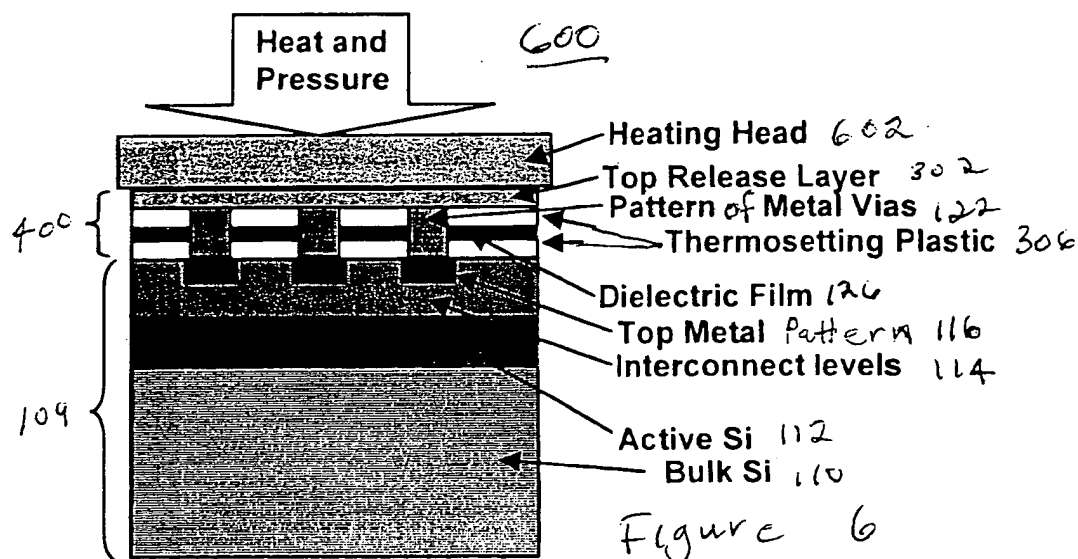


Figure 6

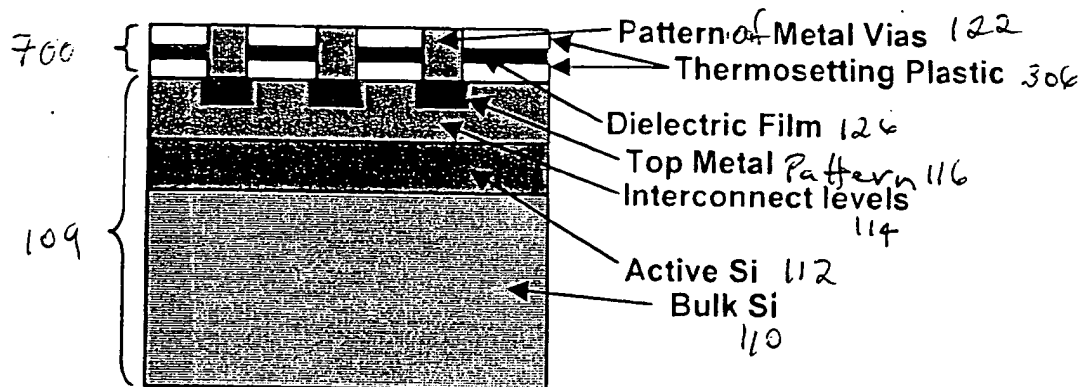


Figure 7

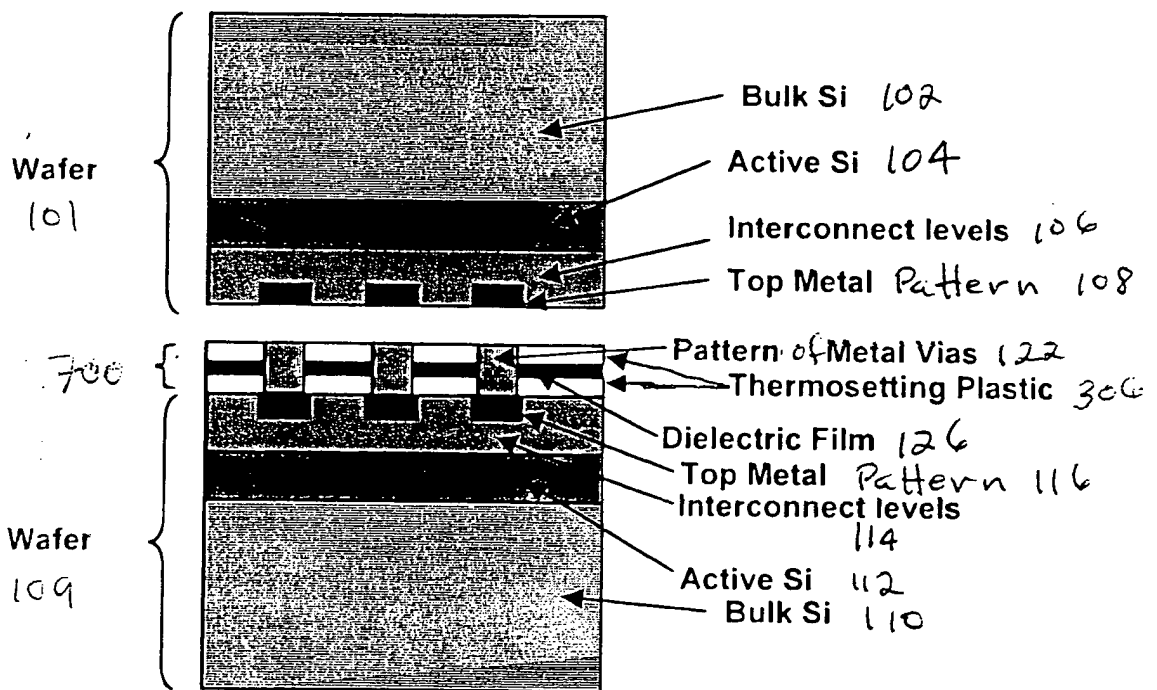


Figure 8

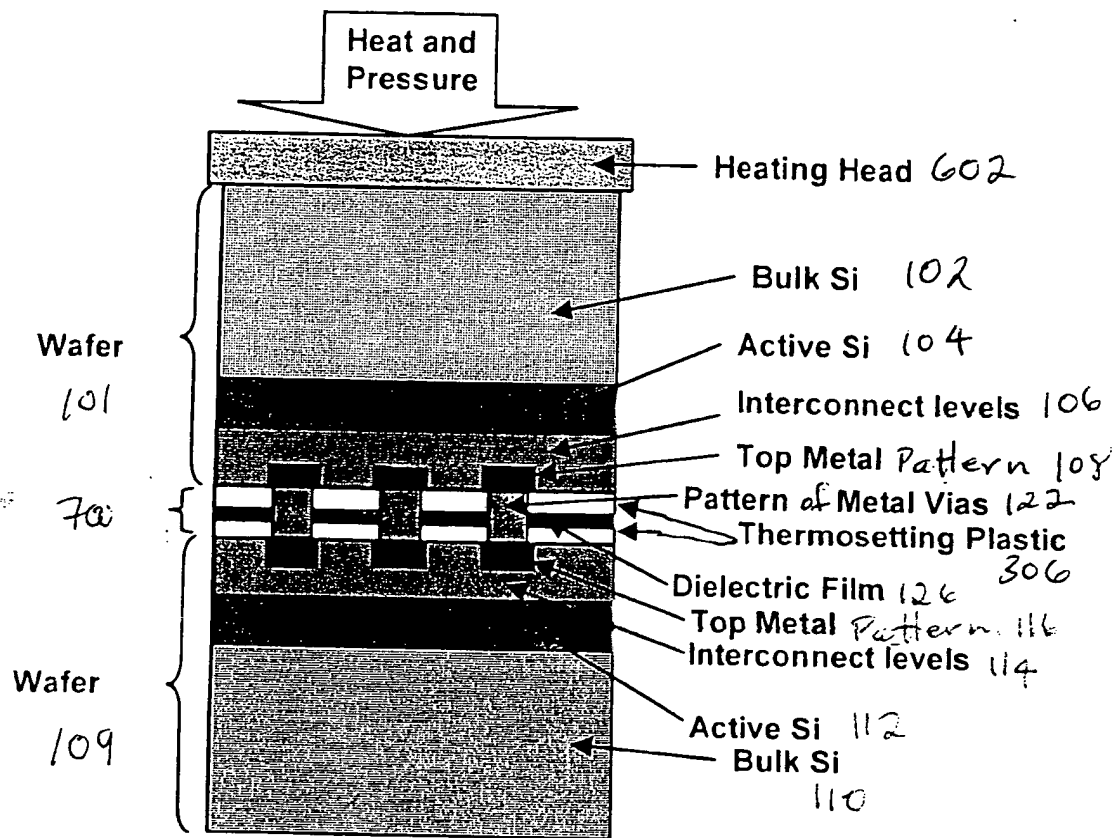
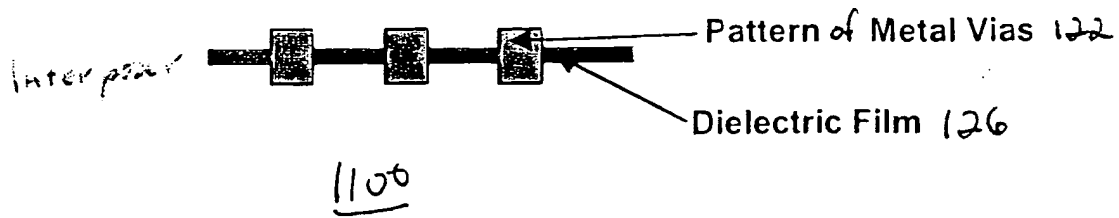


Figure 9

Figure 11



Align pattern of metal vias 122 with the metal pattern 108 and the metal pattern 116

~ 1002

Heat the assembly 1200 is heated to electrically couple the metal pattern 108 to the metal pattern 116

~ 1004

Dispose a thermosetting plastic in liquid or fluid form in the gaps 1304 and/or 1306 and cure thermosetting plastic

~ 1006

Figure 10 1000

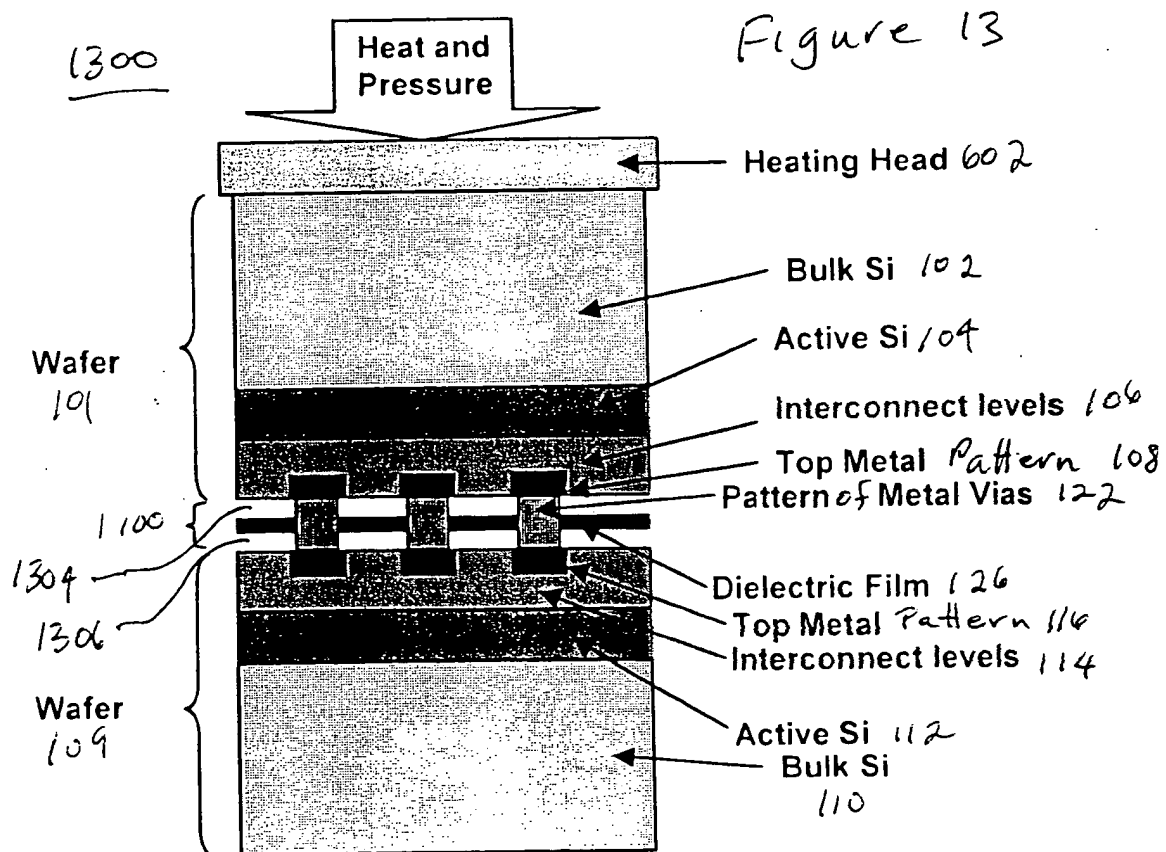
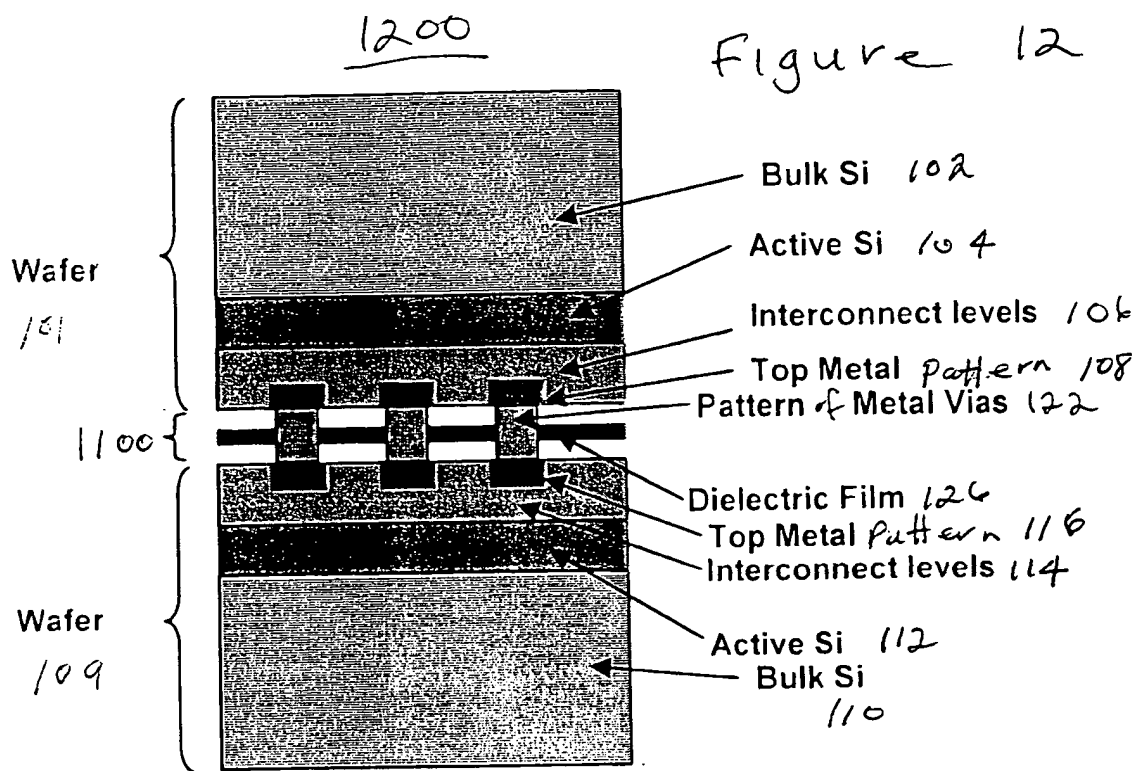


Figure 14 1400

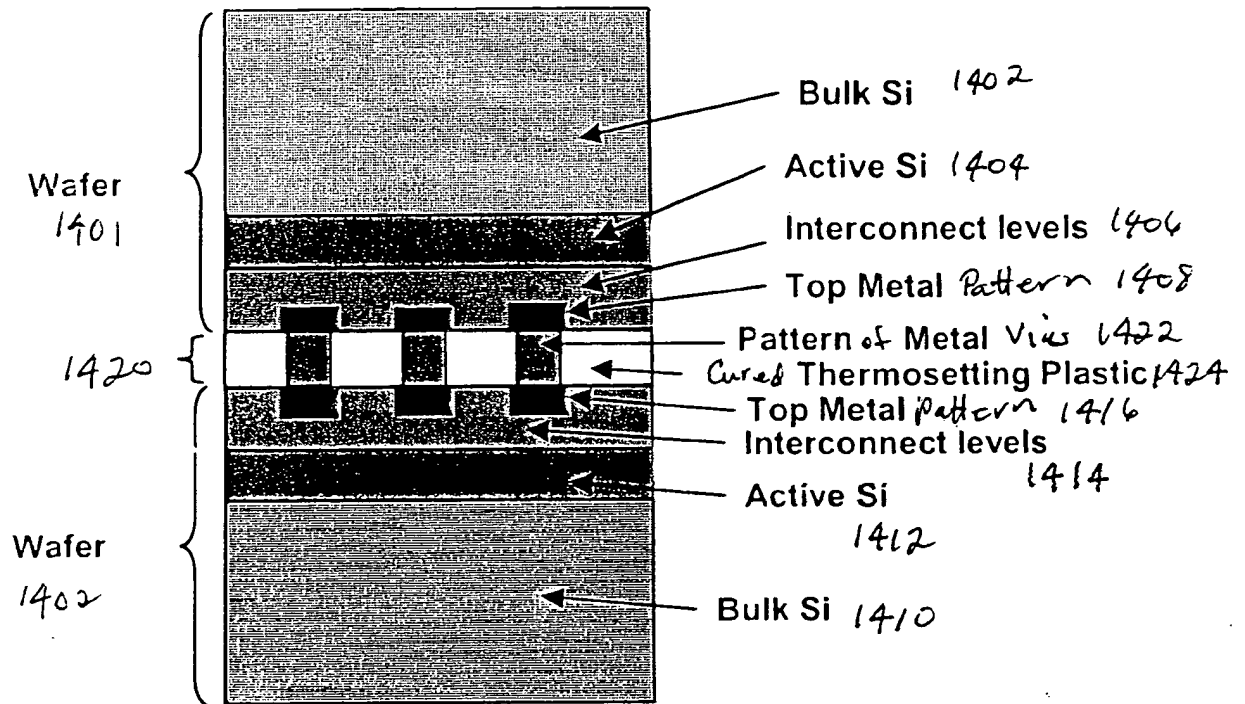
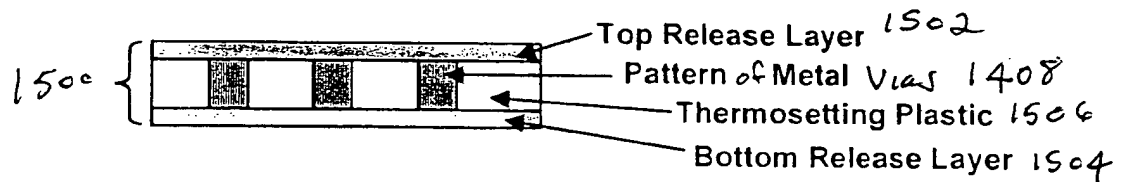


Figure 15



1600

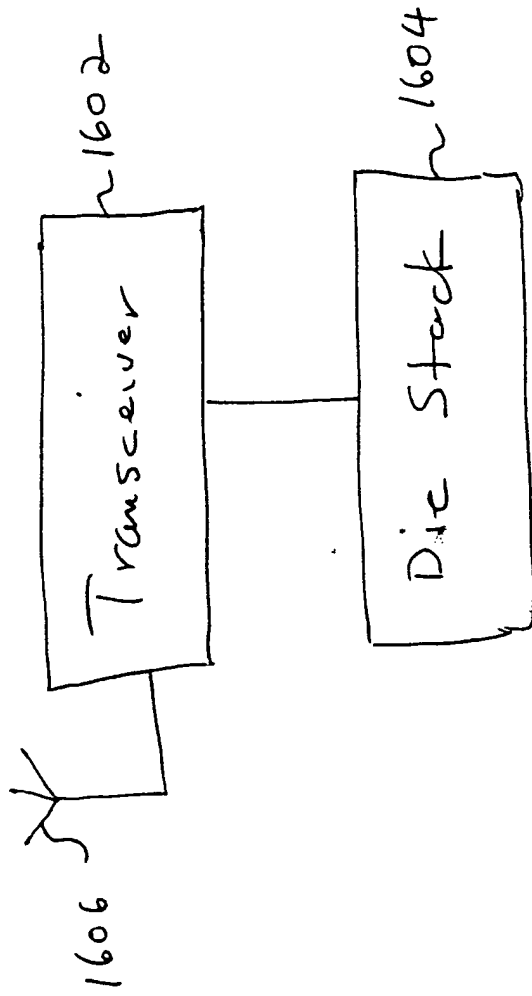


Figure 16